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PRESS RELEASE

MacDermid Alpha Addresses Advanced Packaging Materials Challenges at SEMICON Taiwan 2026

SEMICON Taiwan 2026 | Booth #L0800 | Taipei, Taiwan

WATERBURY, Conn., August 26, 2026 — MacDermid Alpha Electronics Solutions will highlight materials and process technologies designed to address the performance, reliability and manufacturing challenges created by artificial intelligence (AI), high-performance computing (HPC) and increasingly complex advanced packaging architectures at SEMICON Taiwan 2026, September 2–4 at the TaiNEX Nangang Exhibition Center in Taipei.

As AI and HPC drive greater device density and packaging complexity, semiconductor manufacturers face increasingly interconnected materials challenges spanning performance, yield, cost, supply chain resilience and evolving environmental requirements. MacDermid Alpha brings together materials and process technologies across wafer fabrication, advanced interconnect metallization and die attach to help manufacturers address these requirements across the semiconductor manufacturing and advanced packaging journey.

Expert Presentation Explores Advanced Packaging Materials

At the TechXPOT Forum, **Dr. Yun Hao Hsieh, Global Product Manager**, will present *Electrochemical Materials Driving the Future of Advanced Packaging*. The presentation will explore how AI, HPC and high-bandwidth memory (HBM) are changing material requirements, including bump coplanarity, void-free through-silicon via (TSV) filling, grain control for hybrid bonding and mitigation of alpha-particle-induced soft errors.

Materials Innovation Across the Semiconductor Journey

At booth #L0800, MacDermid Alpha will feature **ViaForm® dual damascene chemistries** for complex advanced-node interconnect architectures, its **Low Alpha Tin portfolio** for applications requiring mitigation of alpha-particle-induced soft errors, and **MICROFAB® EVF NiBAR**, a boric acid-free barrier plating technology for wafer-level applications.

As silver-price volatility increases pressure on semiconductor manufacturers to improve cost predictability and supply resilience, **ALPHA® ATROX® CD 560-1** provides a silver-alternative die attach solution designed to reduce dependence on traditional silver-filled materials while supporting high-throughput manufacturing and reliable package performance. **ATROX® Zero PFAS** conductive die attach materials will also be featured.

“At MacDermid Alpha, we’re excited to be at the forefront of innovation, with our cutting-edge chemistries and materials enabling the complex architectures required for advanced packaging and AI infrastructure,” comments Brian Gokey, Vice President Wafer Level Packaging at MacDermid Alpha. “By combining materials and process expertise, we help customers address evolving challenges in performance, reliability and manufacturing. Our leadership in barrier technologies and advanced metallization positions us to support the industry as interconnects scale to increasingly advanced nodes, helping enable the next generation of AI and high-performance computing.”

Visit MacDermid Alpha at **booth #L0800**, and attend Dr. Hsieh's TechXPOT presentation on September 3, 14:00 – 14:20 at Hall 1 4F TechXPOT Stage.

Explore the technologies being featured at SEMICON Taiwan 2026 on the MacDermid Alpha event page.

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MacDermid Alpha Electronics Solutions

MacDermid Alpha Electronics Solutions, a business unit of Element Solutions Inc, is a global leader in high-performance specialty chemicals, materials, and process technologies for every stage of the electronics manufacturing process. With expertise spanning circuitry formation, wafer-level packaging, circuit board assembly, semiconductor assembly, and film and smart surfaces, MacDermid Alpha delivers advanced, sustainable, and integrated solutions that drive innovation and reliability across the electronics supply chain. Operating worldwide and backed by more than a century of innovation, the organization supports a broad range of industries including automotive, consumer electronics, data infrastructure, high-performance computing, and telecommunications enabling next-generation electronics.

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